AO4802, AO4802L

Dual N-Channel Enhancement Mode Field Effect Transistor

General Description

The AO4802 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. They offer operation over a wide gate drive range from 1.8V to 12V. The two devices may be used individually, in parallel or to form a bidirectional blocking switch. AO4802L (Green Product) is offered in a lead-free package.

Features

V_{DS} (V) = 30V

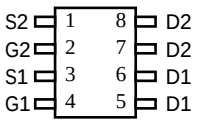
I_D = 7A

$R_{DS(ON)}$ < 26mΩ (V_{GS} = 10V)

$R_{DS(ON)}$ < 30mΩ (V_{GS} = 4.5V)

$R_{DS(ON)}$ < 40mΩ (V_{GS} = 2.5V)

$R_{DS(ON)}$ < 70mΩ (V_{GS} = 1.8V)



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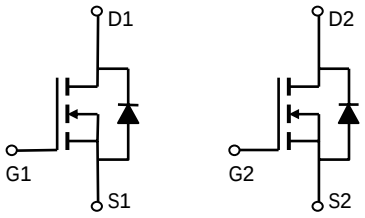

Absolute Maximum Ratings T_A=25°C unless otherwise noted				
Parameter		**Symbol**	**Maximum**	**Units**
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±12	V
Continuous Drain Current [A]	T_A=25°C	I_D	7	A
	T_A=70°C		6	
Pulsed Drain Current [B]		I_{DM}	40	
Power Dissipation	T_A=25°C	P_D	2	W
	T_A=70°C		1.44	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics					
Parameter		**Symbol**	**Typ**	**Max**	**Units**
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	48	62.5	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		74	110	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	35	40	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=24V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±12V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	0.6	0.8	1	V
$I_{D(ON)}$	On state drain current	V_{GS}=4.5V, V_{DS}=5V	30			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=7A		22	26	mΩ
		T_J=125°C		28	36	
		V_{GS}=4.5V, I_D=6A		25	30	mΩ
		V_{GS}=2.5V, I_D=4A		34	40	mΩ
		V_{GS}=1.8V, I_D=2A		52	70	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=5A	12	17		S
V_{SD}	Diode Forward Voltage	I_S=1A		0.66	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		767		pF
C_{oss}	Output Capacitance			111		pF
C_{rss}	Reverse Transfer Capacitance			82		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		1.3		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=4.5V, V_{DS}=15V, I_D=7A		10		nC
Q_{gs}	Gate Source Charge			1.2		nC
Q_{gd}	Gate Drain Charge			3.1		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=2.2Ω, R_{GEN}=6Ω		5		ns
t_r	Turn-On Rise Time			5.5		ns
$t_{D(off)}$	Turn-Off DelayTime			39		ns
t_f	Turn-Off Fall Time			4.7		ns
t_{rr}	Body Diode Reverse Recovery time	I_F=5A, dI/dt=100A/µs		15		ns
Q_{rr}	Body Diode Reverse Recovery charge	I_F=5A, dI/dt=100A/µs		7.1		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any a given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

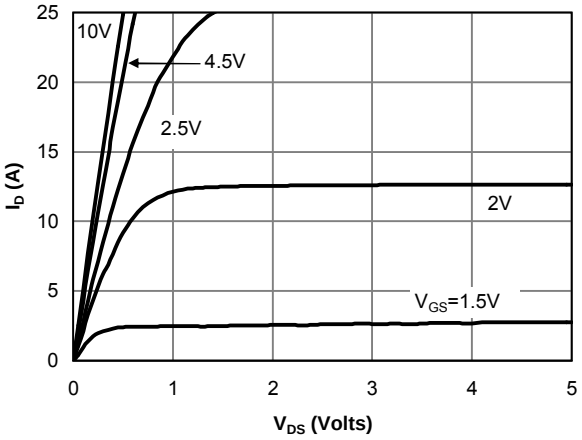

Fig 1: On-Region Characteristics

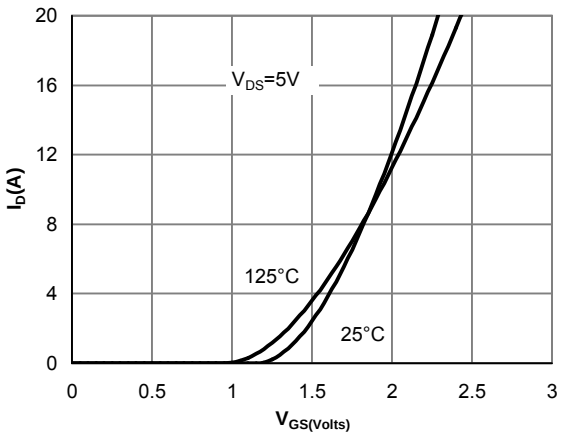

Figure 2: Transfer Characteristics

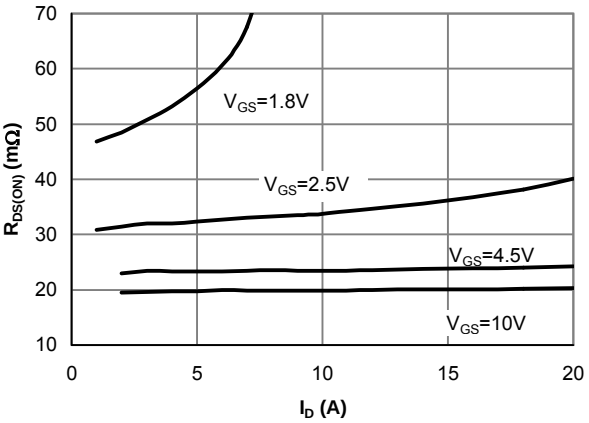

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

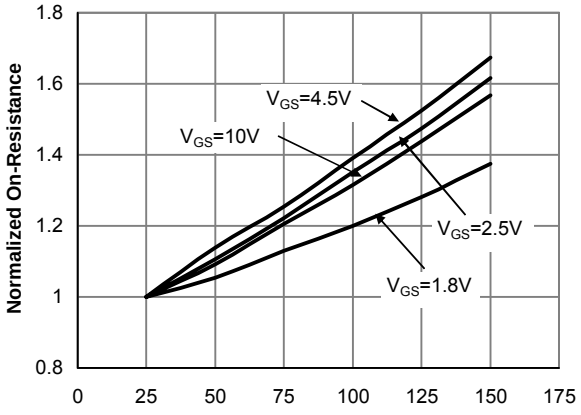

Figure 4: On-Resistance vs. Junction Temperature

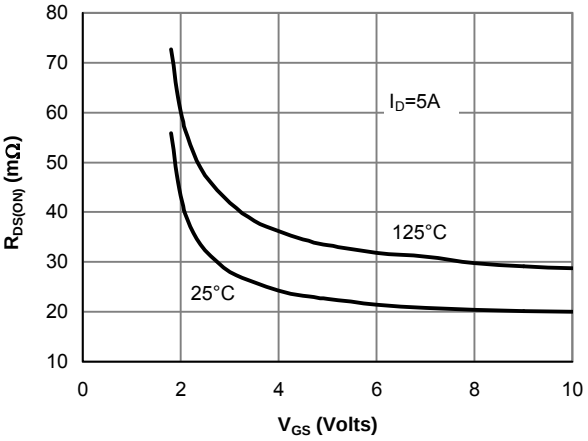

Figure 5: On-Resistance vs. Gate-Source Voltage

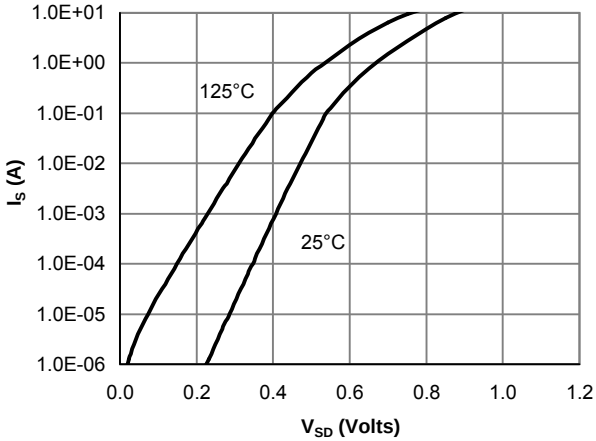

Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

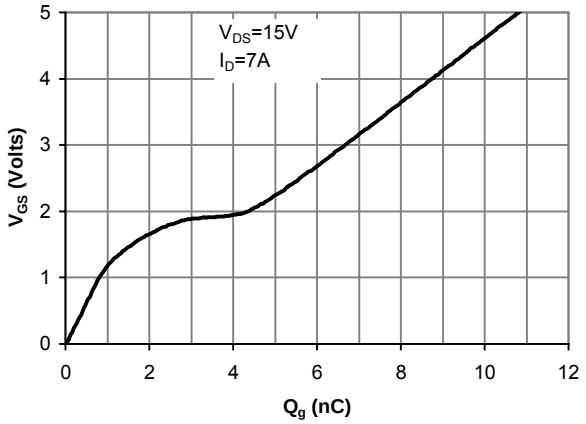

Figure 7: Gate-Charge Characteristics

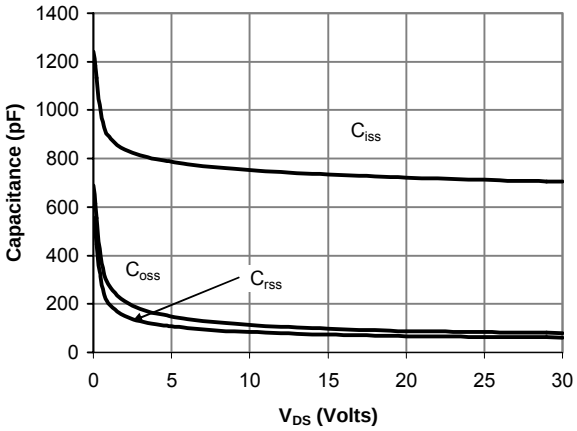

Figure 8: Capacitance Characteristics

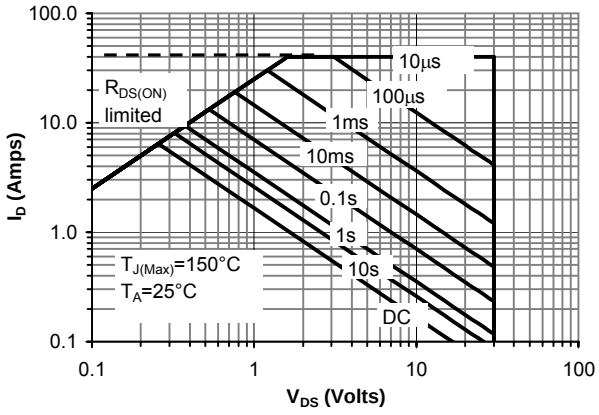

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

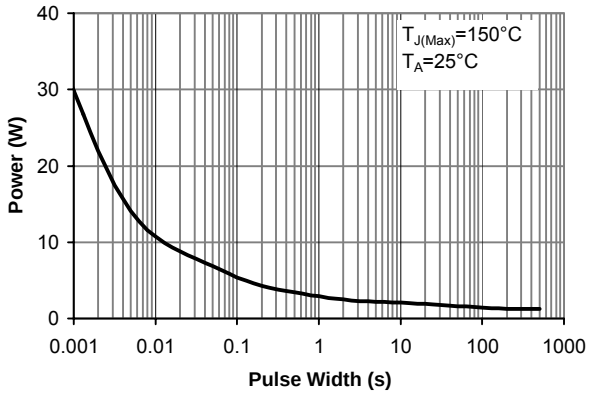

Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

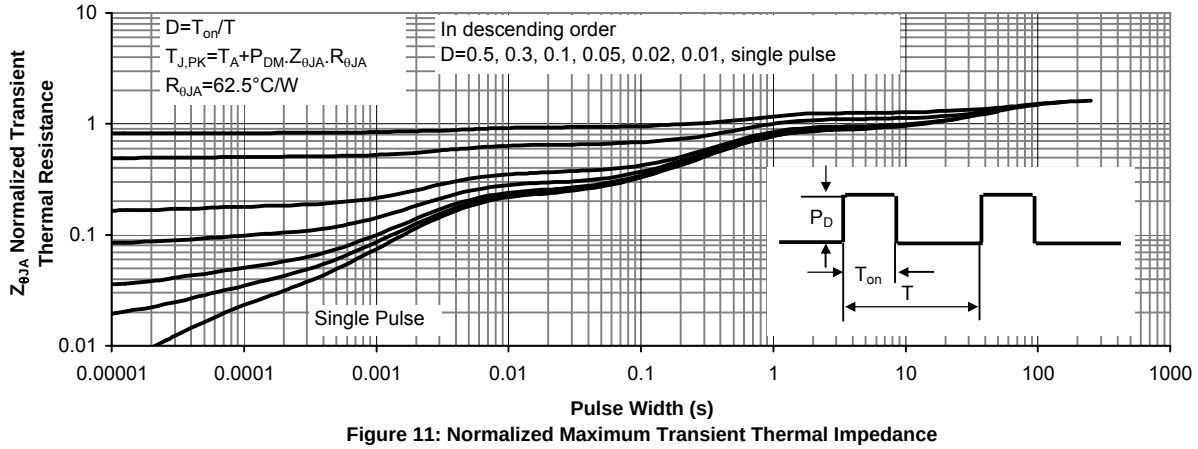

Figure 11: Normalized Maximum Transient Thermal Impedance